

BALL GRID ARRAY TYPE IC SOCKET

ABSTRACT OF THE DISCLOSURE

Solder balls are sufficiently offset in the horizontal direction from fixing portions while their positional accuracy is ensured, and signal paths are shortened in a ball grid array type IC socket. Contacts fixed to contact housing apertures of a housing include base portions (fixing portions), contact arms, and tines that extend from the lower ends of the base portions toward a circuit board. The contact arms protrude so as to extend upward and then are bent unidirectionally. The tines are constituted by transition portions that link solder ball connection portions to the base portions, while offsetting the solder ball connection portions in the same direction as the contact arms. The transition portions include vertical portions which are substantially perpendicular to the solder ball connection portions. The vertical portions prevent movement of the solder balls, thereby preventing positional misalignment and deformation thereof.

Fig. 1